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# MC74LCX86

## Low-Voltage CMOS Quad 2-Input XOR Gate

### With 5 V-Tolerant Inputs

The MC74LCX86 is a high performance, quad 2-input XOR gate operating from a 2.3 to 3.6 V supply. High impedance TTL compatible inputs significantly reduce current loading to input drivers while TTL compatible outputs offer improved switching noise performance. A  $V_I$  specification of 5.5 V allows MC74LCX86 inputs to be safely driven from 5.0 V devices.

Current drive capability is 24 mA at the outputs.

#### Features

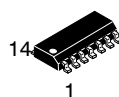
- Designed for 2.3 to 3.6 V  $V_{CC}$  Operation
- 5.0 V Tolerant Inputs – Interface Capability With 5.0 V TTL Logic
- LVTTTL Compatible
- LVCMOS Compatible
- 24 mA Balanced Output Sink and Source Capability
- Near Zero Static Supply Current (10  $\mu$ A) Substantially Reduces System Power Requirements
- Latchup Performance Exceeds 500 mA
- ESD Performance: Human Body Model >2000 V  
Machine Model >200 V
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant



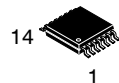
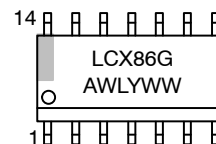
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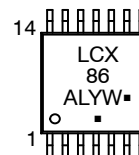
#### MARKING DIAGRAMS



SOIC-14  
D SUFFIX  
CASE 751A



TSSOP-14  
DT SUFFIX  
CASE 948G



A = Assembly Location  
L, WL = Wafer Lot  
Y, YY = Year  
W, WW = Work Week  
G or ▪ = Pb-Free Package

(Note: Microdot may be in either location)

#### ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 4 of this data sheet.

# MC74LCX86

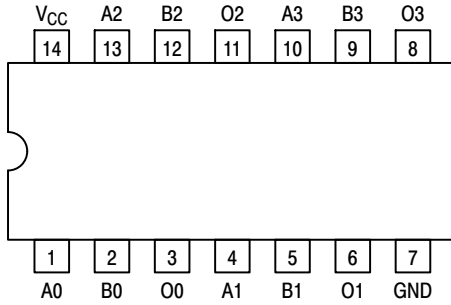


Figure 1. Pinout: 14-Lead (Top View)

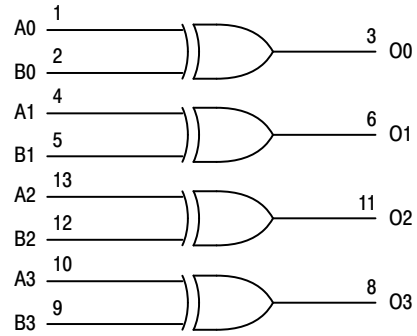


Figure 2. Logic Diagram

## PIN NAMES

Pins	Function
An, Bn	Data Inputs
On	Outputs

## TRUTH TABLE

Inputs		Outputs
An	Bn	On
L	L	L
L	H	H
H	L	H
H	H	L

## MAXIMUM RATINGS

Symbol	Parameter	Value	Condition	Units
$V_{CC}$	DC Supply Voltage	-0.5 to +7.0		V
$V_I$	DC Input Voltage	$-0.5 \leq V_I \leq +7.0$		V
$V_O$	DC Output Voltage	$-0.5 \leq V_O \leq V_{CC} + 0.5$	Note 1	V
$I_{IK}$	DC Input Diode Current	-50	$V_I < GND$	mA
$I_{OK}$	DC Output Diode Current	-50	$V_O < GND$	mA
		+50	$V_O > V_{CC}$	mA
$I_O$	DC Output Source/Sink Current	$\pm 50$		mA
$I_{CC}$	DC Supply Current Per Supply Pin	$\pm 100$		mA
$I_{GND}$	DC Ground Current Per Ground Pin	$\pm 100$		mA
$T_{STG}$	Storage Temperature Range	-65 to +150		$^{\circ}C$
MSL	Moisture Sensitivity		Level 1	

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

1. Output in HIGH or LOW State.  $I_O$  absolute maximum rating must be observed.

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## RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Typ	Max	Units
$V_{CC}$	Supply Voltage Operating Data Retention Only	2.0	3.3	3.6	V
		1.5	3.3	3.6	
$V_I$	Input Voltage	0		5.5	V
$V_O$	Output Voltage (HIGH or LOW State)	0		$V_{CC}$	V
$I_{OH}$	HIGH Level Output Current, $V_{CC} = 3.0\text{ V} - 3.6\text{ V}$			-24	mA
$I_{OL}$	LOW Level Output Current, $V_{CC} = 3.0\text{ V} - 3.6\text{ V}$			24	mA
$I_{OH}$	HIGH Level Output Current, $V_{CC} = 2.7\text{ V} - 3.0\text{ V}$			-12	mA
$I_{OL}$	LOW Level Output Current, $V_{CC} = 2.7\text{ V} - 3.0\text{ V}$			12	mA
$T_A$	Operating Free-Air Temperature	-40		+85	°C
$\Delta t/\Delta V$	Input Transition Rise or Fall Rate, $V_{IN}$ from 0.8 V to 2.0 V, $V_{CC} = 3.0\text{ V}$	0		10	ns/V

## DC ELECTRICAL CHARACTERISTICS

Symbol	Characteristic	Condition	$T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$		Units
			Min	Max	
$V_{IH}$	HIGH Level Input Voltage (Note 2)	$2.7\text{ V} \leq V_{CC} \leq 3.6\text{ V}$	2.0		V
$V_{IL}$	LOW Level Input Voltage (Note 2)	$2.7\text{ V} \leq V_{CC} \leq 3.6\text{ V}$		0.8	V
$V_{OH}$	HIGH Level Output Voltage	$2.7\text{ V} \leq V_{CC} \leq 3.6\text{ V}; I_{OH} = -100\ \mu\text{A}$	$V_{CC} - 0.2$		V
		$V_{CC} = 2.7\text{ V}; I_{OH} = -12\text{ mA}$	2.2		
		$V_{CC} = 3.0\text{ V}; I_{OH} = -18\text{ mA}$	2.4		
		$V_{CC} = 3.0\text{ V}; I_{OH} = -24\text{ mA}$	2.2		
$V_{OL}$	LOW Level Output Voltage	$2.7\text{ V} \leq V_{CC} \leq 3.6\text{ V}; I_{OL} = 100\ \mu\text{A}$		0.2	V
		$V_{CC} = 2.7\text{ V}; I_{OL} = 12\text{ mA}$		0.4	
		$V_{CC} = 3.0\text{ V}; I_{OL} = 16\text{ mA}$		0.4	
		$V_{CC} = 3.0\text{ V}; I_{OL} = 24\text{ mA}$		0.55	
$I_{OFF}$	Power Off Leakage Current	$V_{CC} = 0, V_{IN} = 5.5\text{ V}$ or $V_{OUT} = 5.5\text{ V}$		10	$\mu\text{A}$
$I_{IN}$	Input Leakage Current	$V_{CC} = 3.6\text{ V}, V_{IN} = 5.5\text{ V}$ or GND		$\pm 5$	$\mu\text{A}$
$I_{CC}$	Quiescent Supply Current	$V_{CC} = 3.6\text{ V}, V_{IN} = 5.5\text{ V}$ or GND		10	$\mu\text{A}$
$\Delta I_{CC}$	Increase in $I_{CC}$ per Input	$2.3 \leq V_{CC} \leq 3.6\text{ V}; V_{IH} = V_{CC} - 0.6\text{ V}$		500	$\mu\text{A}$

2. These values of  $V_I$  are used to test DC electrical characteristics only.

## AC CHARACTERISTICS ( $t_R = t_F = 2.5\text{ ns}; C_L = 50\text{ pF}; R_L = 500\ \Omega$ )

Symbol	Parameter	Waveform	Limits			Units
			$T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$			
			$V_{CC} = 3.0\text{ V}$ to $3.6\text{ V}$		$V_{CC} = 2.7\text{ V}$	
			Min	Max	Max	
$t_{PLH}$ $t_{PHL}$	Propagation Delay Input to Output	1,2	1.5	6.5	7.0	ns
			1.5	6.5	7.0	
$t_{OSHL}$ $t_{OSLH}$	Output-to-Output Skew (Note 3)			1.0		ns
				1.0		

3. Skew is defined as the absolute value of the difference between the actual propagation delay for any two separate outputs of the same device. The specification applies to any outputs switching in the same direction, either HIGH-to-LOW ( $t_{OSHL}$ ) or LOW-to-HIGH ( $t_{OSLH}$ ); parameter guaranteed by design.

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## DYNAMIC SWITCHING CHARACTERISTICS

Symbol	Characteristic	Condition	T <sub>A</sub> = +25°C			Units
			Min	Typ	Max	
V <sub>OLP</sub>	Dynamic LOW Peak Voltage (Note 4)	V <sub>CC</sub> = 3.3 V, C <sub>L</sub> = 50 pF, V <sub>IH</sub> = 3.3 V, V <sub>IL</sub> = 0 V		0.8		V
V <sub>OLV</sub>	Dynamic LOW Valley Voltage (Note 4)	V <sub>CC</sub> = 3.3 V, C <sub>L</sub> = 50 pF, V <sub>IH</sub> = 3.3 V, V <sub>IL</sub> = 0 V		0.8		V

4. Number of outputs defined as "n". Measured with "n-1" outputs switching from HIGH-to-LOW or LOW-to-HIGH. The remaining output is measured in the LOW state.

## CAPACITIVE CHARACTERISTICS

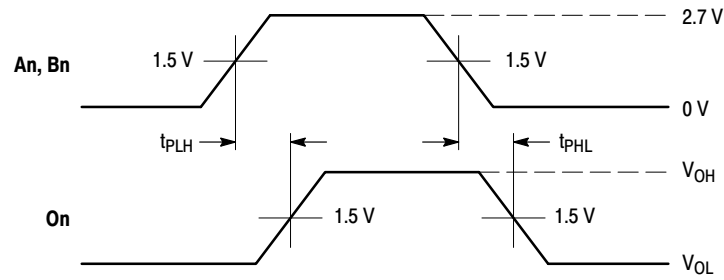
Symbol	Parameter	Condition	Typical	Units
C <sub>IN</sub>	Input Capacitance	V <sub>CC</sub> = 3.3 V, V <sub>I</sub> = 0 V or V <sub>CC</sub>	7	pF
C <sub>OUT</sub>	Output Capacitance	V <sub>CC</sub> = 3.3 V, V <sub>I</sub> = 0 V or V <sub>CC</sub>	8	pF
C <sub>PD</sub>	Power Dissipation Capacitance	10 MHz, V <sub>CC</sub> = 3.3 V, V <sub>I</sub> = 0 V or V <sub>CC</sub>	25	pF

## ORDERING INFORMATION

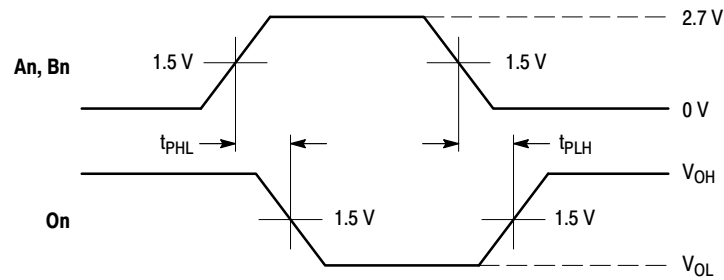
Device	Package	Shipping <sup>†</sup>
MC74LCX86DR2G	SOIC-14 (Pb-Free)	2500 Tape & Reel
MC74LCX86DTR2G	TSSOP-14 (Pb-Free)	2500 Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

# MC74LCX86

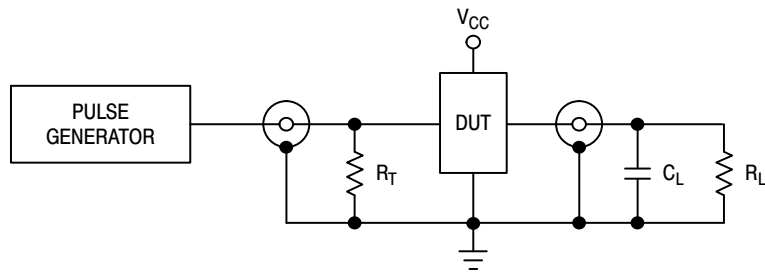


**WAVEFORM 1 - NON-INVERTING PROPAGATION DELAYS**  
 $t_R = t_F = 2.5 \text{ ns}$ , 10% to 90%;  $f = 1 \text{ MHz}$ ;  $t_W = 500 \text{ ns}$



**WAVEFORM 2 - INVERTING PROPAGATION DELAYS**  
 $t_R = t_F = 2.5 \text{ ns}$ , 10% to 90%;  $f = 1 \text{ MHz}$ ;  $t_W = 500 \text{ ns}$

**Figure 3. AC Waveforms**



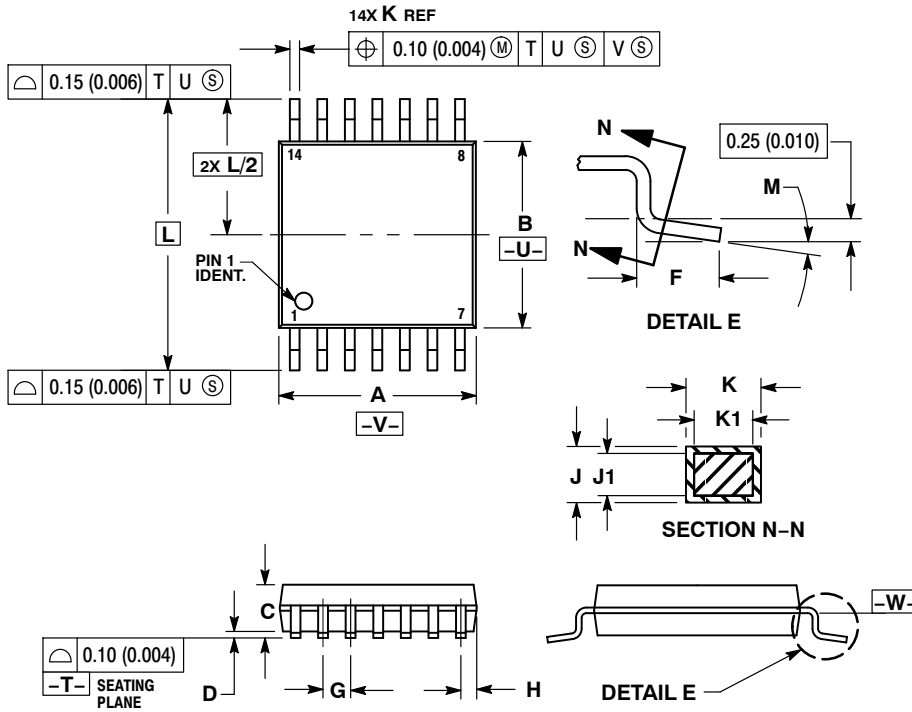
$C_L = 50\text{pF}$  or equivalent (Includes jig and probe capacitance)  
 $R_L = R_1 = 500 \Omega$  or equivalent  
 $R_T = Z_{OUT}$  of pulse generator (typically  $50 \Omega$ )

**Figure 4. Test Circuit**

# MC74LCX86

## PACKAGE DIMENSIONS

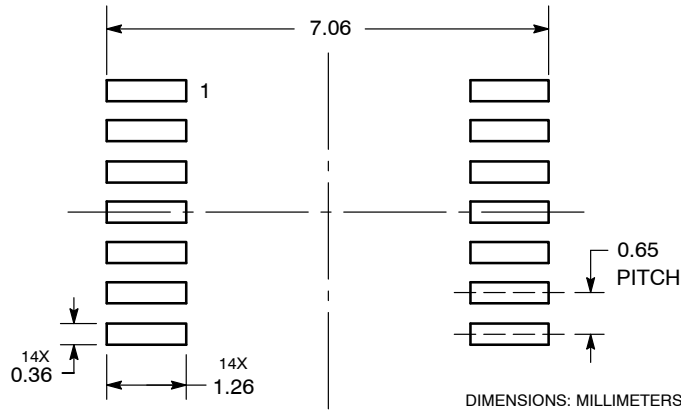
TSSOP-14  
CASE 948G  
ISSUE B



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: MILLIMETER.
  3. DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
  4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
  5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
  6. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
  7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.90	5.10	0.193	0.200
B	4.30	4.50	0.169	0.177
C	---	1.20	---	0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65 BSC		0.026 BSC	
H	0.50	0.60	0.020	0.024
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40 BSC		0.252 BSC	
M	0°	8°	0°	8°

### SOLDERING FOOTPRINT\*

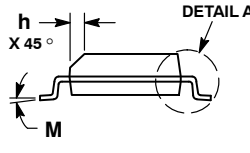
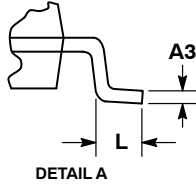
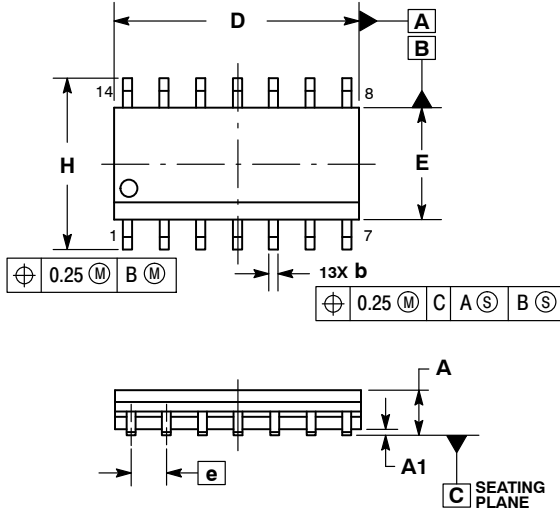


\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

# MC74LCX86

## PACKAGE DIMENSIONS

SOIC-14 NB  
CASE 751A-03  
ISSUE K

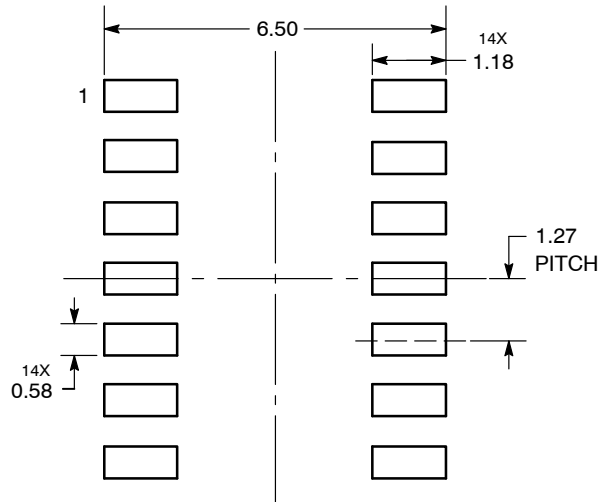


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.13 TOTAL IN EXCESS OF AT MAXIMUM MATERIAL CONDITION.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD PROTRUSIONS.
5. MAXIMUM MOLD PROTRUSION 0.15 PER SIDE.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	1.35	1.75	0.054	0.068
A1	0.10	0.25	0.004	0.010
A3	0.19	0.25	0.008	0.010
b	0.35	0.49	0.014	0.019
D	8.55	8.75	0.337	0.344
E	3.80	4.00	0.150	0.157
e	1.27 BSC		0.050 BSC	
H	5.80	6.20	0.228	0.244
h	0.25	0.50	0.010	0.019
L	0.40	1.25	0.016	0.049
M	0°	7°	0°	7°

### SOLDERING FOOTPRINT\*



DIMENSIONS: MILLIMETERS

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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